



Click [here](#) for the 3D model.

General Information

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| Series | SMD Comm COG HV |
| Style | SMD Chip |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| Typical Component Weight | 25 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

| | |
|----------------------|-----------------|
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| T | 1mm +/-0.10mm |
| S | 1.5mm MIN |
| B | 0.5mm +/-0.25mm |
| Case Code (EIA / mm) | 1206 / 3216 |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 330mm, Plastic Tape |
| Packaging Quantity | 10000 |

Specifications

| | |
|--|------------------------|
| Capacitance | 150 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 1000 VDC |
| Dielectric Withstanding Voltage | 1,200 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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